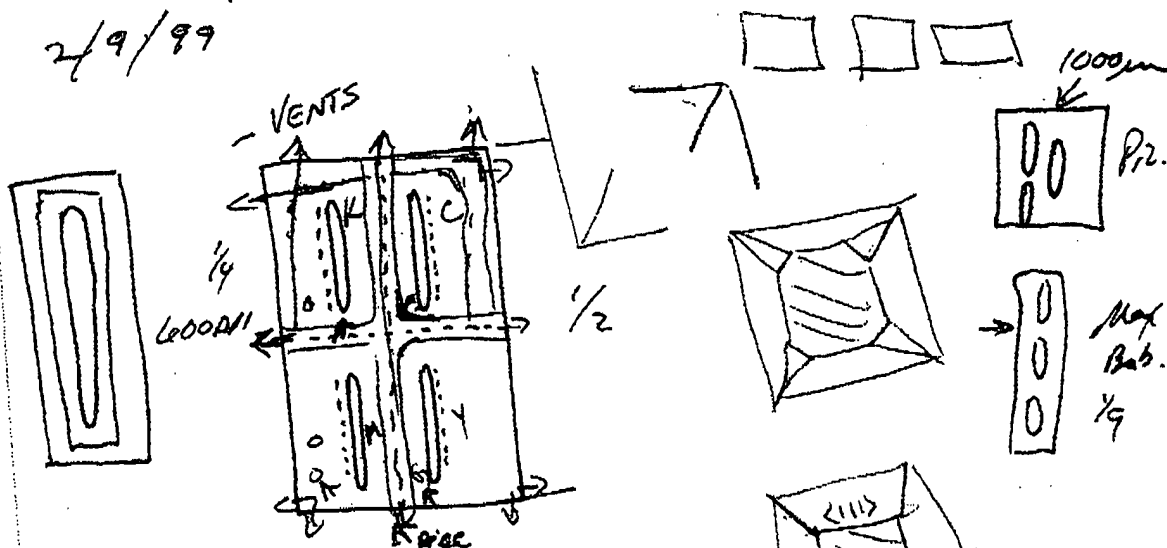
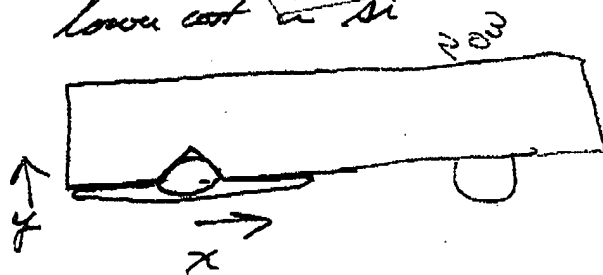


2/9/99



Micro-machining a base ablate a Dice  
 trench around ink vics to provide  
 containment for die bond.  
 - thinner bonding in  $x$  &  $y$   
 lower cost in Si

KENT UBERACKER



Problem:

Fragility of the chip

Jim Spivey 7/2/99  
 Carl Sullivan 2/9/99

BEST AVAILABLE COPY